

MINI EDGE-CARD SOCKET MEC1 SERIES

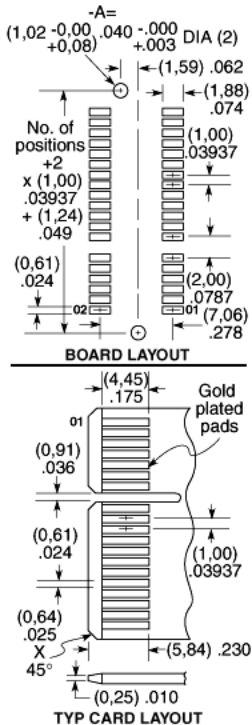
SPECIFICATIONS

For complete specifications see www.samtec.com?MEC1

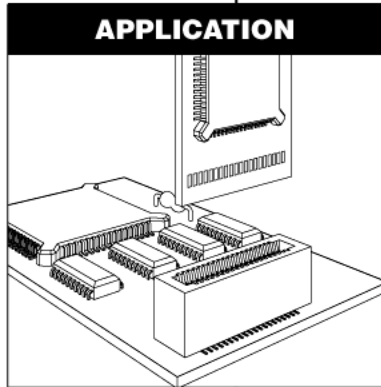
- Insulator Material:** Black LCP
- Contact Material:** BeCu
- Plating:** Sn or Au over 50µ" (1,27µm) Ni
- Operating Temp Range:** -55°C to +125°C
- Current Rating:** 2A @ 80°C ambient
- Voltage Rating:** 300 VAC
- Insertion Depth:** (5,84mm) .230" to (8,13mm) .320"

Processing:

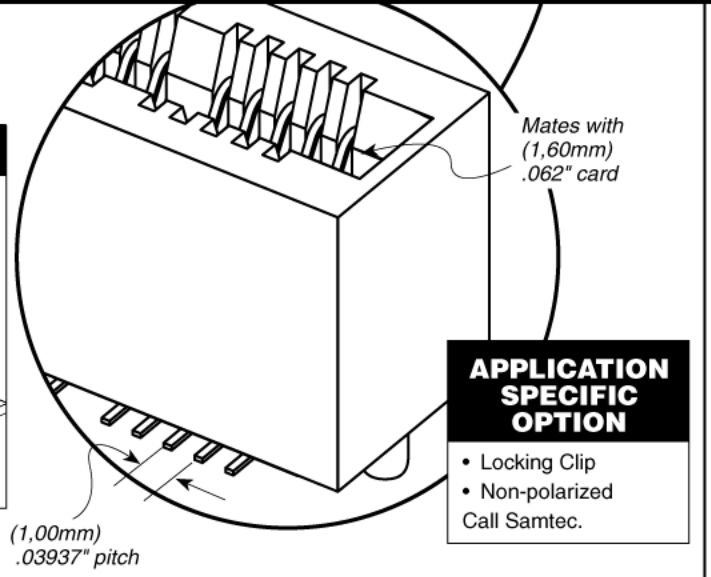
- Max Processing Temp:** 230°C for 60 seconds, or 260°C for 20 seconds 3x with Matte Sn plating
- Lead-Free Solderable:** Yes, with Matte Sn
- SMT Lead Coplanarity:** (0,10mm) .004" max (05-20) (0,15mm) .006" max (30-70)
- Suggested PCB Layouts:** For reference only. Please contact Samtec or go to www.samtec.com?MEC1 for recommended PCB layout.



Mates with:
(1,60mm) .062" card



Note: Some sizes, styles and options are non-standard, non-returnable.



APPLICATION SPECIFIC OPTION

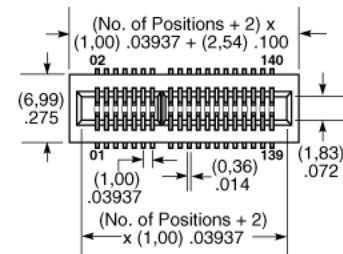
- Locking Clip
 - Non-polarized
- Call Samtec.



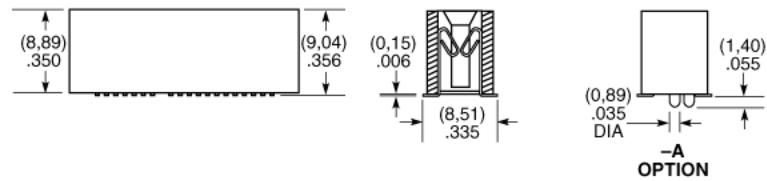
05, 08, 20, 30, 40, 50, 60, 70

- S or -SM**
= 30µ" (0,76µm) Gold on contact, Tin (-S) or Matte Tin (-SM) on tail
- L or -LM**
= 10µ" (0,25µm) Gold on contact, Tin (-L) or Matte Tin (-LM) on tail
- F or -FM**
= Gold flash on contact, Tin (-F) or Matte Tin (-FM) on tail

- A**
= Alignment Pin Metal or plastic at Samtec discretion.
- K**
= (7,87mm) .310" DIA Polyimide film Pick & Place Pad
- TR**
= Tape & Reel



POSITIONS PER ROW	POLARIZED POSITIONS
-05	3, 4
-08	5, 6
-20	15, 16
-30	21, 22
-40	31, 32
-50	41, 42
-60	31, 32, 63 & 64
-70	53, 54, 115 & 116



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM